Preferred Device

## **Silicon Controlled Rectifiers**

## **Reverse Blocking Thyristors**

Designed primarily for half–wave ac control applications, such as motor controls, heating controls, and power supplies; or wherever half–wave, silicon gate–controlled devices are needed.

- Blocking Voltage to 800 Volts
- On–State Current Rating of 16 Amperes RMS
- High Surge Current Capability 160 Amperes
- Rugged Economical TO-220AB Package
- Glass Passivated Junctions for Reliability and Uniformity
- Minimum and Maximum Values of I<sub>GT</sub>, V<sub>GT</sub>, and I<sub>H</sub> Specified for Ease of Design
- High Immunity to dv/dt 100 V/µsec Minimum at 125°C
- Device Marking: Logo, Device Type, e.g., MCR16N, Date Code

**MAXIMUM RATINGS** (T<sub>J</sub> =  $25^{\circ}$ C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage(1) $(T_J = -40 \text{ to } 125^{\circ}\text{C}, \text{ Sine Wave, 50 to}$ $60 \text{ Hz}, \text{ Gate Open})$ MCR16N	<sup>V</sup> drm, <sup>V</sup> rrm	800	Volts
On-State RMS Current (180° Conduction Angles; T <sub>C</sub> = 80°C)	IT(RMS)	16	A
Peak Non-repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T <sub>J</sub> = 125°C)	ITSM	160	A
Circuit Fusing Consideration (t = 8.3 ms)	l <sup>2</sup> t	106	A <sup>2</sup> sec
Forward Peak Gate Power (Pulse Width $\leq$ 1.0 $\mu$ s, T <sub>C</sub> = 80°C)	PGM	5.0	Watts
Forward Average Gate Power (t = 8.3 ms, $T_C = 80^{\circ}C$ )	PG(AV)	0.5	Watts
Forward Peak Gate Current (Pulse Width $\leq$ 1.0 $\mu$ s, T <sub>C</sub> = 80°C)	IGM	2.0	A
Operating Junction Temperature Range	Тj	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

(1) V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

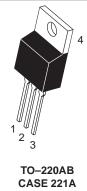


#### **ON Semiconductor**

http://onsemi.com

SCRs 16 AMPERES RMS 800 VOLT





STYLE 3

PIN ASSIGNMENT
Cathode
Anode
Gate
Anode

#### ORDERING INFORMATION

Device	Package	Shipping
MCR16N	TO220AB	50 Units/Rail

**Preferred** devices are recommended choices for future use and best overall value.

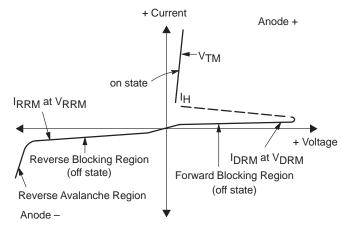
#### THERMAL CHARACTERISTICS

Thermal Resistance — Junction to Case — Junction to Ambient		R <sub>θ</sub> JC R <sub>θ</sub> JA	1.5 62.5		°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10	imum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds		260		°C
ELECTRICAL CHARACTERISTICS (TJ = 25°C unless otherwise noted	)				
Characteristic	Symb	ol Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Peak Repetitive Forward or Reverse Blocking Current $T_J = 25^{\circ}C$ $(V_{AK} = Rated V_{DRM} \text{ or } V_{RRM}, Gate Open)$ $T_J = 125^{\circ}C$	IDRN IRRN		_	0.01 2.0	mA
ON CHARACTERISTICS					
Peak Forward On–State Voltage* (I <sub>TM</sub> = 32 A)		1 —	—	1.7	Volts
Gate Trigger Current (Continuous dc) (V <sub>D</sub> = 12 V, R <sub>L</sub> = 100 $\Omega$ )		2.0	10	20	mA
Gate Trigger Voltage (Continuous dc) (V <sub>D</sub> = 12 V, R <sub>L</sub> = 100 $\Omega$ )		- 0.5	0.65	1.0	Volts
Hold Current (Anode Voltage = 12 V, Initiating Current = 200 mA, Gate Open)		4.0	25	40	mA
Latch Current $(V_D = 12 \text{ V}, \text{ Ig} = 200 \text{ mA})$		IL —		60	mA
DYNAMIC CHARACTERISTICS	•	•	-	•	
Critical Rate of Rise of Off–State Voltage ( $V_D$ = Rated $V_{DRM}$ , Exponential Waveform, Gate Open, T <sub>J</sub> = 125°C)		t 100	300	-	V/µs
Critical Rate of Rise of On–State Current (I <sub>PK</sub> = 50 A, Pw = 30 μs, diG/dt = 1 A/μsec, Igt = 50 mA)		t —	-	50	A/μs

\*Indicates Pulse Test: Pulse Width  $\leq$  2.0 ms, Duty Cycle  $\leq$  2%.

### Voltage Current Characteristic of SCR

Symbol	Parameter
VDRM	Peak Repetitive Off State Forward Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Off State Reverse Voltage
IRRM	Peak Reverse Blocking Current
VTM	Peak On State Voltage
Ι <sub>Η</sub>	Holding Current



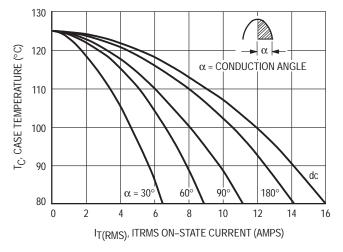


Figure 1. Typical RMS Current Derating

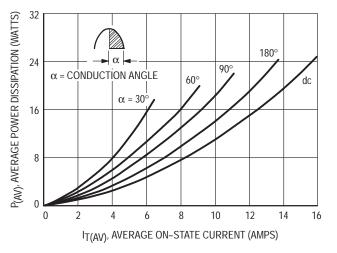
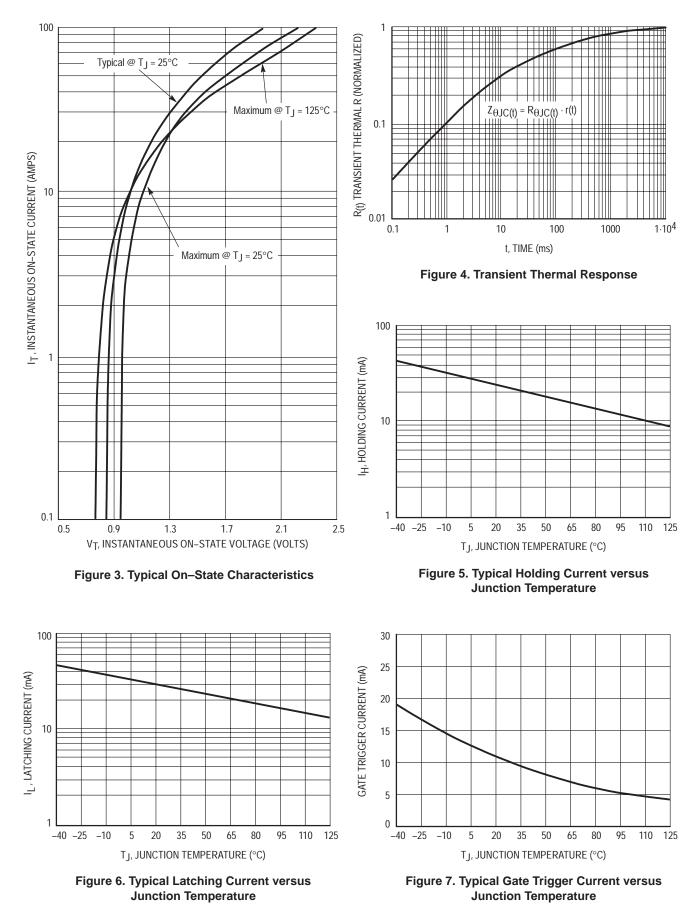


Figure 2. On State Power Dissipation



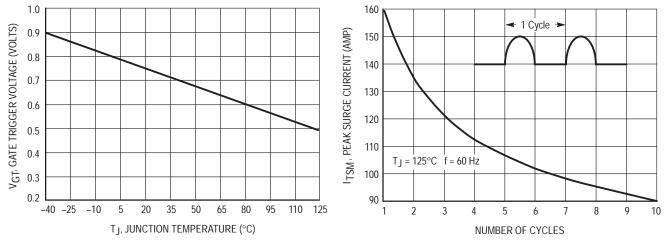
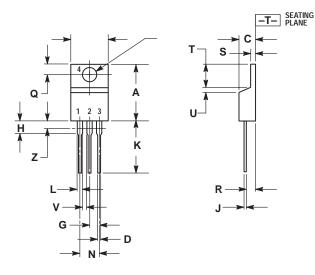


Figure 8. Typical Gate Trigger Voltage versus Junction Temperature

Figure 9. Maximum Non–Repetitive Surge Current

#### PACKAGE DIMENSIONS

TO-220AB CASE 221A-09 ISSUE Z



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN MAX	
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
К	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Ζ		0.080		2.04

STYLE 3: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE

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## <u>Notes</u>

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